PCN Number:		20201201000.1					PCN Date:				Jan. 11, 2021				
Title: Qualification of MIHO8 as an additional Fab site option for select devices															
Customer Contact:			PCN Manager									Quality Services			
Proposed 1 st Ship Date:			Apr. 11, 2021				Estimated Sample				le	Date provided at			
			7.01.11, 2021				Availability: sa				san	ample request.			
Change Type: Assembly Site				Assembly Process Asse					embly Materials						
Design			Electrical Spe										nical Specification		
Test Site				Packing/Ship									st Process		
Wafer Bump Site				Wafer Bump										Bump Process	
☐ Wafer Fab Site				Wafer Fab Ma								Wafer Fab Process			
				Part number change											
						PCN	De	tails							
Description Toylor Instru						ounge the a	!:6	iontion of i	to MILL	٦.) 6	م اسط م		n facility ac an	
						ounce the q elected dev								n facility as an	
additional	water i	ab sour	CC 10		10 3	elected dev	ices	iisteu iii ti	16 1100	Ju	ici	. All	CLCL	J Section.	
	Cu	rrent F	ab S	ite				Additio				I Fa	b Si	te	
Current	Fab	Proc	ess			Wafer	A	dditional	P	ro	00	ess		Wafer	
Site					D	iameter		Fab Site						Diameter	
MAINEF	MAINEFAB ABCD5HV				200 mm			MIHO8	Α	ABCD5HV				200 mm	
Oual detail	Ougl details are previded in the Ougl Data Costion														
Qual details are provided in the Qual Data Section. Reason for Change:															
Continuity of Supply															
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):															
None															
	to proc	luct ide	entific	cat	ion	resulting	fror	n this PCN	N:						
- Changes (.o p. oc	idet ide		-		resulting									
Current:															
Current Chip Site Chip Site		Origin Code (20L)			С	Chip Site Country Co				e (21	.L)	Chip Site City			
MAINEFAB			CUA				USA						South Portland		
New Fab		Chin	Cito	0=	ain	Codo (201)	T ~	Thin Cita Ca				- (21	1.3	Chin Cita City	
New Chip Site Chip Site MIHO8			Origin Code (20L) MH8				Chip Site Country Co				e (21	.L)	Chip Site City Ibaraki		
MILIT	00			- 1	1110	,			JFIN					IDalaki	
Sample pro	oduct s	hipping	label	(no	ot a	ctual produ	ct la	bel)							
		11 3	_	Ì				,							
INSTRUMENTS (1P) SN74LS07NSR															
MADE IN: Malaysia (Q) 2000 (D) 0336															
MSL 2 /260C/1 YEAR SEAL DT															
MSL 1 /2	35C/UNL	IM 03/	29/04	4	3		Š	(P)			75	5234	83	512	
ITEM:	. ,.	\ TO - 4	750		200		14	(2P) REV	: SHE	()	V) 21	L) C	333 0:0:0		
LBL: 5	A (L)T0:1	150			*		(22L) AS				L) A			

ISO1042DW

ISO1042DWR

ISO1042BDWV

ISO1042BDWVR

Product Affected: ISO1042BDW

ISO1042BDWR

ISO1042DWV

ISO1042DWVR

Qualification Report

Approve Date 13-Oct-2020

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: ISO1042QDWQ1	QBS Product Reference: ISO1042DW (PG1.1)	QBS Product Reference: ISO1042DW(PG1.0)	QBS Process Reference: ISO7741FQDWQ1	QBS Process Reference: TCAN1042HVDRQ1 (PG 2.0).	QBS Package Reference: ISO1042DW (PG1.1)	QBS Package Reference: ISO1042DW(PG1.0)
AC	Autoclave 121C	96 Hours	-	1/77/0	2/154/0	3/231/0	3/231/0	1/77/0	2/154/0
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	-	-	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	3/2400/0	3/2400/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	3/231/0	3/231/0	-	1/77/0
НВМ	ESD - HBM (All Pins)	8000 V	-	1/3/0	-	-	-	-	-
НВМ	ESD - HBM (Bus Pins Only)	16000 V	-	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	1/77/0	2/154/0	3/231/0	-	1/77/0	2/154/0
HTOL	Life Test, 150C	300 Hours	-	-			3/231/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	1/77/0	2/154/0	-	3/135/0	1/77/0	2/154/0
HTSL	High Temp Storage Bake 175C	500 Hours	-	-	-	3/231/0	-	-	-
LU	Latch-up	(Per JESD78)	-	1/6/0	-	-	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	-	3/231/0	3/231/0	3/231/0	-
WBP	Bond Pull	Wires	1/76/0	3/182/0	-	3/228/0	3/228/0	3/182/0	-
WBS	Bond Shear	Wires	1/76/0	3/182/0	•	3/228/0	3/228/0	3/182/0	-

- QBS: Qual By Similarity
- Qual Device ISO1042QDWQ1 is qualified at LEVEL3-260C
- Device ISO1042QDWQ1 contains multiple dies.
- Preconditioning was performed for Auto clave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD 47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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